



L860-GL LTE Module

Perfect Wireless Experience

L860-GL LTE Module Technical Specifications

Product Features

- Chipset: Intel XMM7560
- LTE FDD: LTE FDD: Band 1, 2, 3, 4, 5, 7, 8, 12, 13, 14, 17, 18, 19, 20, 21, 25, 26, 28, 29, 30, 32, 66
LTE TDD: B38/39/40/41/42
- UMTS: Band 1, 2, 4, 5, 8
- M.2: 30.0*42.0*2.3 mm
- DL 5CA on 4 bands, DL 256QAM support
- DL-MIMO: 2*2, 4*2, 4*4
- DL 4x4 MIMO: Band 1,2,3,4,7,30,40,41NB, 66
- LAA(Band 46)
- Integrated GNSS
- eSIM interface support
- Operating Voltage: 3.135V~4.4V, Typical 3.3V
- Operating Temperature: -10~+55°C
- Storage Temperature: -40~+85°C
- AT Command Set: 3GPP TS 27.007 and 27.005, proprietary FIBOCOM AT commands
- TX Power:
FDD&TDD LTE: 23dBm
WCDMA: 23.5dBm
- RX Sensitivity:
FDD&TDD LTE: -98dBm~102dBm

Data

- FDD&TDD LTE: 1 Gbps (DL Cat. 16) / 150 Mbps* (UL Cat. 13), *from Q2 '19
- UMTS/HSPA+: 42Mbps DL(Cat 24), 11.5Mbps UL(Cat 7)

Interface

- USIM: 3V/1.8V
- PCIe
- BodySar



Driver

- Windows 10/Linux

Note*: Planning

Approval

- CE / CCC / FCC / GCF / PTCRB etc. 100+ countries certification
- AT&T / Verizon / Sprint / DT / Telefonica / Vodafone / Swisscom / Docomo / K DDI / Softbank / Telstra / Optus

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